

L Number	Hits	Search Text	DB	Time stamp
1	165	(waffle adj pack) or (matrix adj tray)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/23 08:28
-	117	interposer and (semiconductor near2 ic or die) and underfill	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 13:58
-	43	interposer near8 (solder adj ball or solder adj bump) and (semiconductor near2 ic or die) and underfill	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 14:01
-	59	interposer near8 (solder adj ball or solder adj bump) and (semiconductor near2 ic or die) and interposer near4 (underfill or adhesive or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 14:31
-	0	interposer near2 (adhesive or underfill) near7 (wiring near board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 14:32
-	64	interposer near8 (adhesive or underfill) and (adhesive or underfill) near4 (aperture or hole or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:00
-	0	(interposer) and (bonding or bond or adhesive or underfill or dielectric) near4 (low near (temperature or T) near2 (drying or processing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:04
-	0	(die or ic or integrated adj circuit) near4 (printed adj circuit adj board or printed adj wiring adj board or pcb or pwb) and (bonding or bond or adhesive or underfill or dielectric) near4 (low near (temperature or T) near2 (drying or processing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:07
-	49	(die or ic or integrated adj circuit or interposer) near4 (printed adj circuit adj board or printed adj wiring adj board or pcb or pwb) and (bonding or bond or adhesive or underfill or dielectric) near5 (abrading or abrasion or abrade or chemical adj mechanical adj polishing or cmp or grinding or mechanical adj polishing or laser adj ablation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:26
-	1827	(integrated adj circuit or ic or die or printed adj circuit adj board or pcb) and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:29
-	830	(integrated adj circuit or ic or die) and (printed adj circuit adj board or printed adj wiring adj board or pcb) and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:30
-	632	((integrated adj circuit or ic or die) and (printed adj circuit adj board or printed adj wiring adj board or pcb) and interposer) and (bonding or bond)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:32

-	115	((integrated adj circuit or ic or die) and (printed adj circuit adj board or printed adj wiring adj board or pcb) and interposer) and (bonding or bond)) and (layer or dielectric or adhesive or solder or underfill) near3 (bottom or below or top or above or between) near3 interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 16:34
-	28	(die or ic or integrated adj circuit or semiconductor adj device) and (interposer or interposing or interpose) and (wiring adj board or circuit adj board or pwb or pcb) and (underfill or underfilling or flux or adhesive) near5 (interposer or interposing or interpose) near5 (solder or electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 13:49
-	351	(interposer) near5 (bond or connect or bonding or connecting or adhering or adhesive or bonded or connected or adhered or underfill or flux or underfilled or underfilling) near5 (circuit adj board or wiring adj board or pcb or pwb or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 13:53
-	106	((interposer) near5 (bond or connect or bonding or connecting or adhering or adhesive or bonded or connected or adhered or underfill or flux or underfilled or underfilling) near5 (circuit adj board or wiring adj board or pcb or pwb or substrate)) and (chemical adj mechanical adj polishing or cmp or abrading or grinding or mechanical adj polishing or laser or ablation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 13:55
-	8	(low near2 (temperature or temp or t) near3 (drying or curing or dehydrating)) and flip adj chip and (underfill or encapsulant or flux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 11:50
-	18340	curing near4 (drying or dehydrating or water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 11:52
-	12383	curing near2 (drying or dehydrating or water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 11:54
-	1	interposer near6 (singulate or singulated or dicing) near10 (carrier or tape or reel or waffle or matrix)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 11:56
-	9	interposer near6 (singulate or singulated or dicing) and (carrier or tape or reel or waffle or matrix or panel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 12:08
-	74	(singulate or singulating or singulated or singulation) near6 (circuit adj board or wiring adj board or pcb or pwb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 12:43
-	46	((singulate or singulating or singulated or singulation) near6 (circuit adj board or wiring adj board or pcb or pwb)) and (carrier or tape or reel or waffle or matrix)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/22 12:44